

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "OPA627AU/2K5E4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA627AU/2K5E4	NIPDAU	Level-3-260C-168 HR	TI MALAYSIA A/T	D 8	3.91x4.9x1.58	112.1

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001074	11	0.000001	0
Precious Metals	Gold	7440-57-5	0.093092	99.997852	999979	0.08301	830
Precious Metals	Silver	7440-22-4	0.000001	0.001074	11	0.000001	0
Sub-Total			0.093094	100	1000000	0.083012	830
Die Attach Adhesive							
Other Inorganic Materials	Silica	7631-86-9	0.022947	1.999997	20000	0.020462	205
Precious Metals	Silver	7440-22-4	0.791673	69.00001	690000	0.705936	7059
Thermoplastics	Epoxy	85954-11-6	0.332732	28.999993	290000	0.296698	2967
Sub-Total			1.147352	100	1000000	1.023095	10231
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	49.93	99.86	998600	44.52265	445226
Copper and Its Alloys	Iron	7439-89-6	0.05	0.1	1000	0.044585	446
Copper and Its Alloys	Phosphorus	7723-14-0	0.02	0.04	400	0.017834	178
Sub-Total			50	100	1000000	44.585069	445851
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.38048	95.12	951200	0.339275	3393
Precious Metals	Gold	7440-57-5	0.00312	0.78	7800	0.002782	28
Precious Metals	Palladium	7440-05-3	0.0164	4.1	41000	0.014624	146
Sub-Total			0.4	100	1000000	0.356681	3567
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	48.808284	86.000001	860000	43.522414	435224
Other Plastics and Rubber	Carbon Black	1333-86-4	0.170261	0.299999	3000	0.151822	1518
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.312146	0.55	5500	0.278341	2783
Thermoplastics	Epoxy	85954-11-6	7.463127	13.15	131500	6.654881	66549
Sub-Total			56.753818	100	1000000	50.607458	506075
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.750903	100	1000000	3.344685	33447
Sub-Total			3.750903	100	1000000	3.344685	33447
Total			112.145167			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former IIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.